

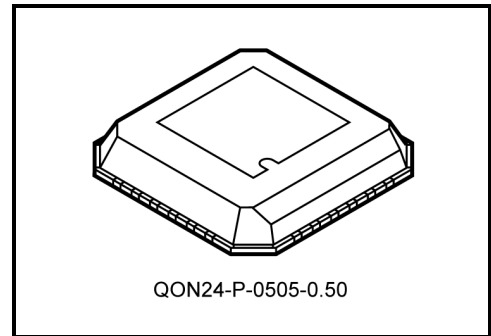
TA8496FL

Magnetic Head R/W IC

This IC enables writing and detection of magnetic recording signals.

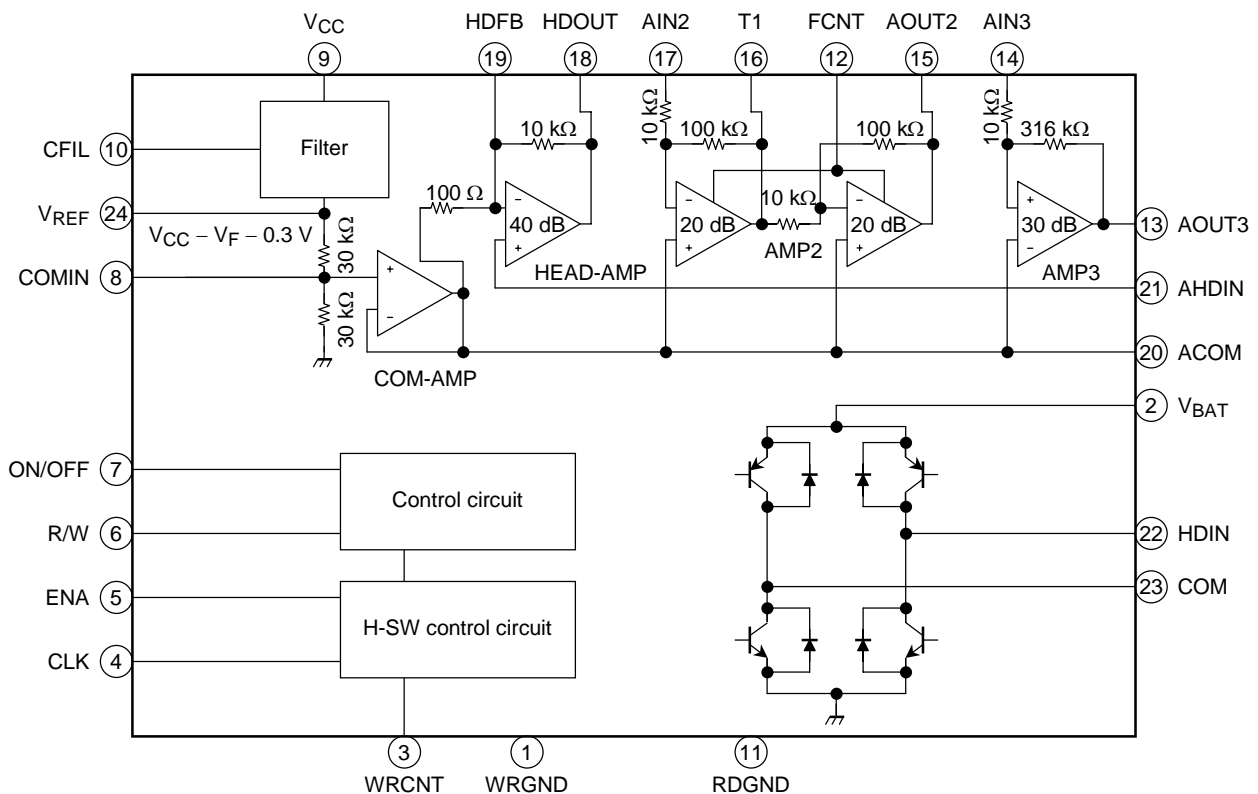
Features

- Operating voltage range: $V_{CC} = 3.5$ to 7 V
 $V_{BAT} = 1.8$ to 7 V
- Output current: $I_{out} = 20$ mA (max)
- Constant current operating function
 $I_{OC} = (0.25 \text{ (V)} \times 160 \text{ (A)})/R_{WR}$ (typ.)



Weight: 0.05 g (typ.)

Block Diagram



Pin Function

Pin Number	Symbol	Description
1	WRGND	GND for write block
2	V _{BAT}	High-switch control power supply
3	WRCNT	Write output setting pin
4	CLK	High-switch operation control signal input
5	ENA	High-switch enable signal input
6	R/W	Read/write select signal input
7	ON/OFF	Chip enable signal input
8	COMIN	Internal reference voltage setting (fine adjustment)
9	V _{CC}	Power supply input pin
10	CFIL	Power supply filter connecting pin (C = 0.1 μF)
11	RDGND	GND for read block
12	FCNT	Cut-off frequency setting pin
13	AOUT3	Amp 3 output
14	AIN3	Amp 3 input
15	AOUT2	Amp 2 output
16	T1	Amp 2 test pin
17	AIN2	Amp 2 input
18	HDOUT	Head amp output
19	HDFB	Head amp feedback input
20	ACOM	COM amp output
21	AHDIN	Head amp output
22	HDIN	Write output
23	COM	Write output
24	V _{ref}	V _{CC} filter output (internal power supply)

Maximum Rating (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Power Supply Voltage	V _{CC}	8	V
	V _{BAT}	8	V
Input Voltage	V _I	6	V
Output Current	I _{OUT}	20	mA
Operating Temperature	T _{opr}	-20 to 70	°C
Storage Temperature	T _{stg}	-50 to 150	°C

Recommended Operating Conditions

Characteristics	Symbol	Rating	Unit
Power Supply Voltage	V _{CC}	3.5 to 7.0	V
	V _{BAT}	1.8 to 7.0	

Functions

Input				Write Unit		Read Unit
ON/OFF	R/W	ENA	CLK	COM	HDin	
H	H	H/L	H/L	∞	∞	Enable
	L	H	H	L	H	Disable
	L	H	L	H	L	Disable
	L	L	L	L	L	Disable
	L	L	H	∞	∞	Disable
L	H/L	H/L	H/L	∞	∞	Disable

∞: High impedance

Electrical Characteristics

Interface Block (unless otherwise is specified, $V_{CC} = 5\text{ V}$, $V_{BAT} = 3\text{ V}$, $T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Input Voltage	V_{IN1-Hi}	—	ENA, ON/OFF	2.5	—	V_{CC}	V
	V_{IN1-Lo}	—	ENA, ON/OFF	—	—	1.0	
	V_{IN2-Hi}	—	CLK, R/W	1.5	—	V_{CC}	
	V_{IN2-Lo}	—	CLK, R/W	—	—	0.5	
Input Current	I_{IN1-Hi}	1	CLK, $V_{IN} = 5\text{ V}$	—	15	25	μA
	I_{IN1-Lo}		CLK, $V_{IN} = 0\text{ V}$	—	-85	-120	
	I_{IN2-Hi}		ENA, $V_{IN} = 5\text{ V}$	—	85	120	
	I_{IN3-Hi}		R/W, $V_{IN} = 5\text{ V}$	—	15	25	
	I_{IN3-Lo}		R/W, $V_{IN} = 0\text{ V}$	—	-85	-120	
	I_{IN4-Hi}		ON/OFF, $V_{IN} = 5\text{ V}$	—	85	120	

Read Block (unless otherwise is specified, $V_{CC} = 5\text{ V}$, $V_{BAT} = 3\text{ V}$, $T_a = 25^\circ\text{C}$)

Characteristics		Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Current Dissipation		I_{CCR}	2	When read block in operation	—	3.2	4.6	mA
		I_{CCO}		When chip disabled (on/off = low or open)	—	0	1	μA
Gain Characteristics	Head amp	G_H	3	—	—	40	—	dB
	Amp 2	G_2		—	—	40	—	
	Amp 3	G_3		—	—	30	—	
Head Amp Input Conversion Noise		E_{n1}	—	$R_g = 0\ \Omega$, $f_c = 19\ \text{kHz}$	—	0.33	(0.64)*	μV_{rms}
		E_{n2}		$R_g = 0\ \Omega$, $f_c = 1.7\ \text{kHz}$	—	0.15	(0.26)*	
Reference Voltage		V_{ACOM}	3	—	1.9	2.0	2.1	V
Output Offset Voltage	Head amp	V_{HOS}	3	—	—	-0.1	± 0.25	V
	Amp 2	V_{2OS}			—	+0.7	± 1.1	
	Amp 3	V_{3OS}			—	+0.1	± 0.25	
Amp 3 Output Voltage Range	Low	V_{3OL}	4	$R_L = 10\ \text{k}\Omega$	—	0.2	—	V
	High	V_{3OH}			—	4.1	—	
Amp 3 Output Current	Output	I_{3OUT}	4	—	2.0	—	—	mA
	Input	I_{3IN}		—	0.1	0.2	0.3	

*: Guaranteed by design. Determined at design and does not change at manufacturing. Test not conducted.

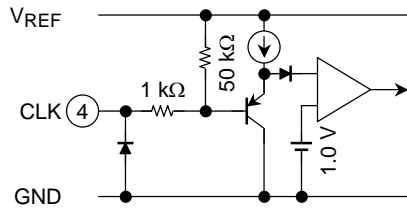
Write Block (unless otherwise is specified, $V_{CC} = 5\text{ V}$, $V_{BAT} = 3\text{ V}$, $T_a = 25^\circ\text{C}$)

Characteristics		Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit	
Current Dissipation		I_{CCw}	2	During write, CLK = Low/High	—	3.7	5.2	mA	
		I_{CCe}		When write enabled	—	1.9	2.8		
		I_{CCB}		When write in break	—	4.4	6.1		
		I_{bat}		During write, reactive current ($R_{WR} = 5\ \text{k}\Omega$)	—	1.4	1.8		
		I_{baB}		When write in break	—	1.0	1.6	μA	
		I_{bar}		During read	—	0	1		
		I_{bao}		When chip disabled (on/off = low or open)	—	0	1		
Set Output Current		I_{OC}	5	$I_{OC} = 10\ \text{mA}$ (at $V_{BAT} = 2.0\ \text{V}$)	$V_{BAT} = 2.0\ \text{V}$	8	10	12	mA
				$V_{BAT} = 5.0\ \text{V}$	—	11	13		
CLK Output Transfer Time		T_{pLH1}	6	0 to 10% (Note1)	—	0.1	—	μs	
		T_{pLH2}		0 to 90% (Note1)	—	0.5	—		
		T_{pHL1}		0 to 10% (Note1)	—	0.1	—		
		T_{pHL2}		0 to 90% (Note1)	—	0.5	—		
ENA Output Transfer Time		T_{pZH1}	6	0 to 10% (Note1)	—	0.3	—	μs	
		T_{pZH2}		0 to 90% (Note1)	—	0.5	—		
		T_{pHZ1}		0 to 10% (Note1)	—	0.3	—		
		T_{pHZ2}		0 to 90% (Note1)	—	0.5	—		

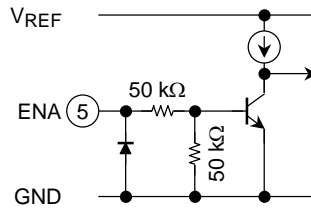
Note 1: Load $R_L = 36\ \Omega$, $C_L = 10\ \text{pF}$

Input/Output Circuit

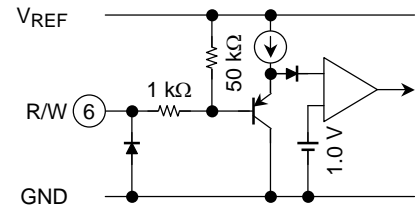
- CLK pin



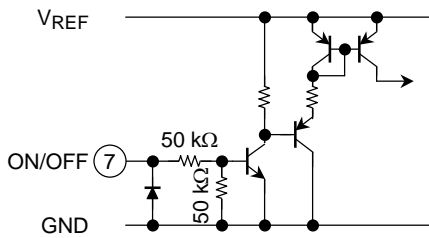
- ENA pin



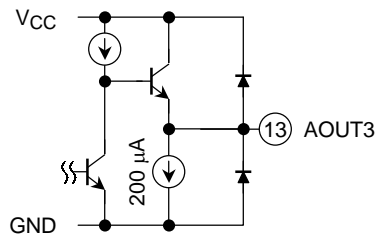
- R/W pin



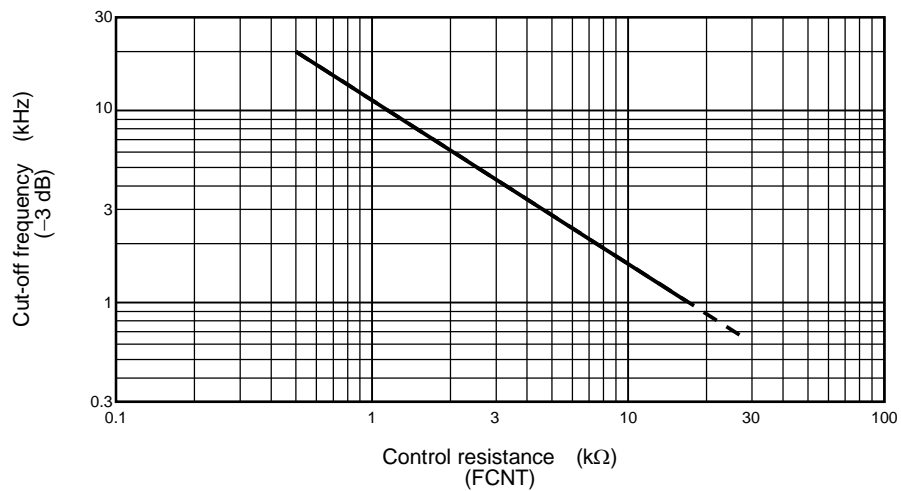
- ON/OFF pin



- AOUT3 pin

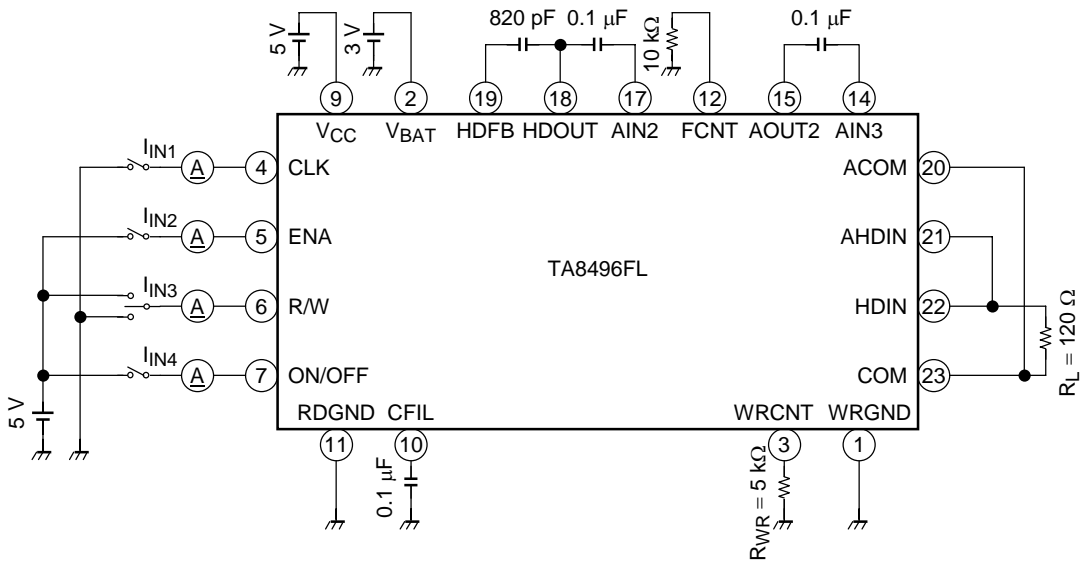


Secondly L.P.F characteristics (amp 2)

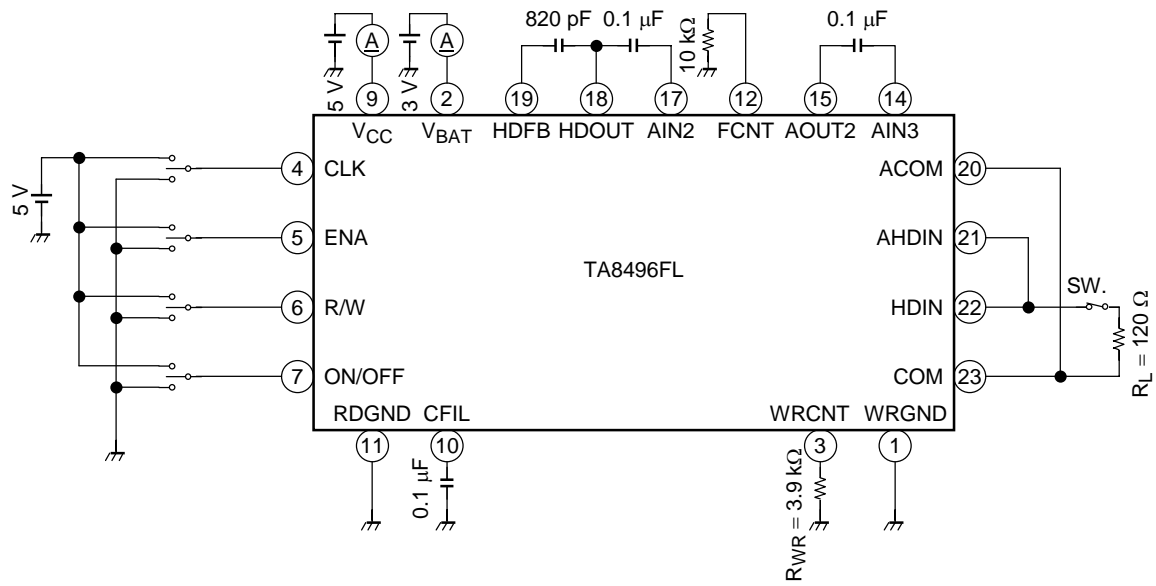


Test Circuit

1. Input Current (I_{IN1} , I_{IN2} , I_{IN3} , I_{IN4})



2. Current Consumption (I_{CCR} , I_{CCO} , I_{CCW} , I_{CCe} , I_{CCB} , I_{bat} , I_{baB} , I_{bar} , I_{bao})

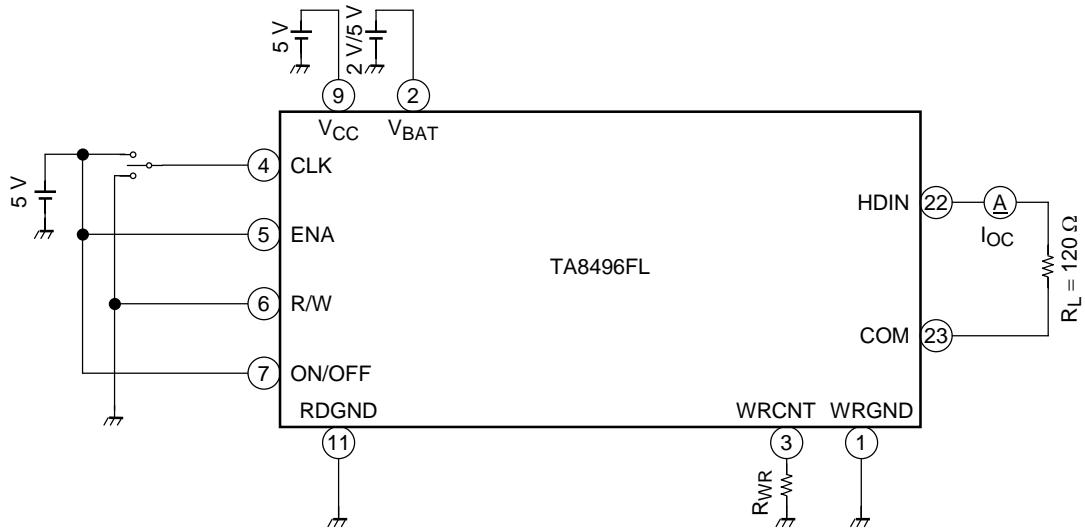


Input Sequence (H = 5 V, L = 0 V)

Current Consumption (V _{CC} , V _{BAT})	ON/OFF	R/W	ENA	CLK
I_{CCR}	H	H	L	H
I_{CCO}	L/OPEN	H	H/L	H
I_{CCW}	H	L	H	H/L
I_{CCe}	H	L	L	H
I_{CCB}	H	L	L	L
I_{bat} (Note2)	H	L	H	H/L
I_{baB}	H	L	L	L
I_{bar}	H	H	H/L	H/L
I_{bao}	L/OPEN	H/L	H/L	H/L

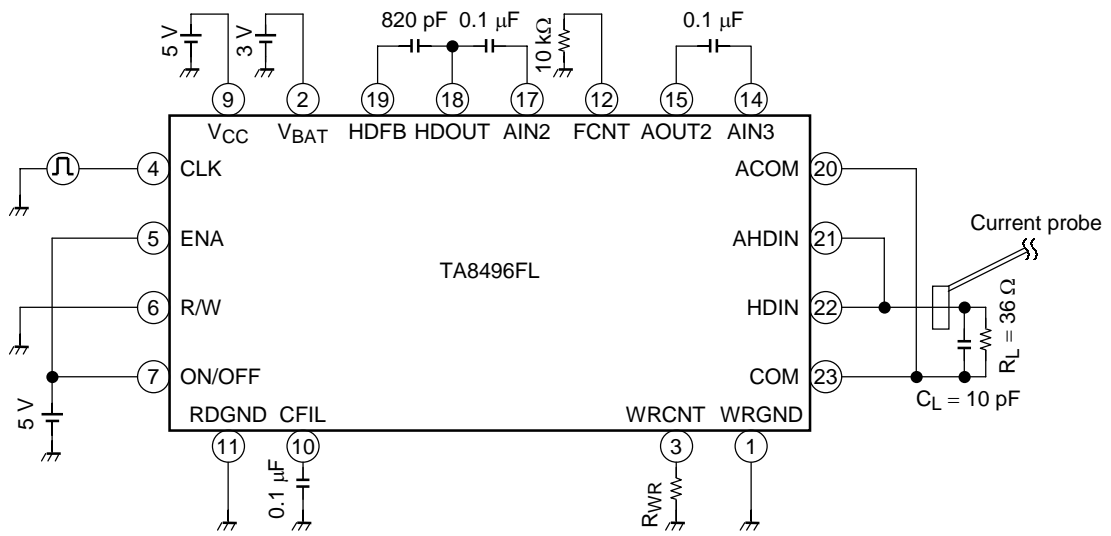
Note 2: SW. OFF

5. Set Output Current (I_{OC})

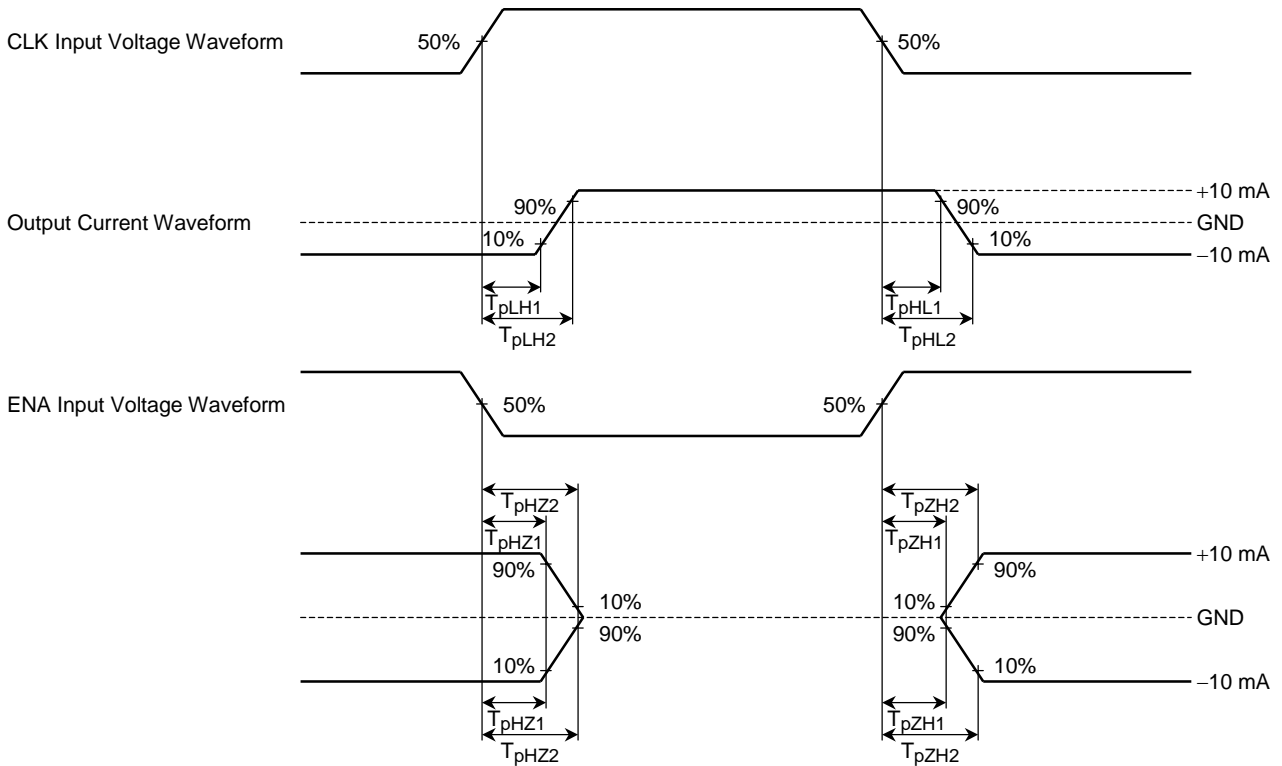


Set R_{WR} so that $I_{OC} = 10 \text{ mA}$ (at $V_{BAT} = 2 \text{ V}$).
 At this time, due to fluctuation in samples, I_{OC} fluctuates in the range of 8 to 12 mA. Also, I_{OC} fluctuates depending on the power supply (V_{BAT}) as follows: $I_{OC} = 10 \text{ mA}$ (at $V_{BAT} = 2 \text{ V}$) \rightarrow $I_{OC} \approx 13 \text{ mA}$ (at $V_{BAT} = 5 \text{ V}$).

6. CLK, ENA Output Propagation Time ($T_{pLH1/2}$, $T_{pHL1/2}$, $T_{pZH1/2}$, $T_{pHZ1/2}$)

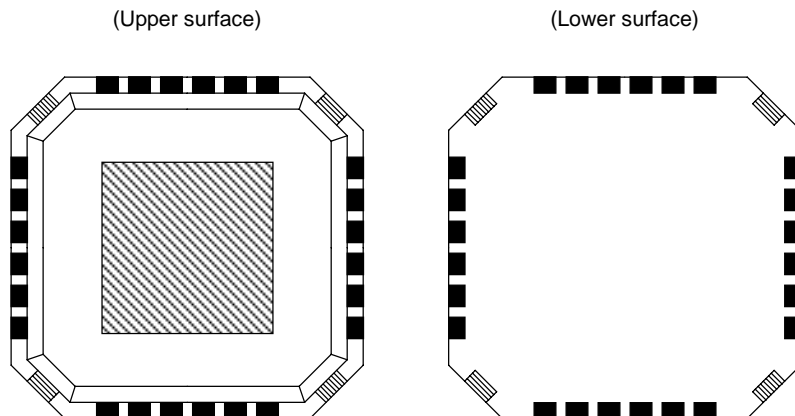


RWR: I_{OC} is set 10 mA.



Requests Concerning Use of QON

Outline Drawing of Package



When using QON, please take into account the following items.

Caution

- (1) Do not carry out soldering on the island section in the four corners of the package (the section shown on the lower surface drawing with diagonal lines) with the aim of increasing mechanical strength.
- (2) The island section exposed on the package surface (the section shown on the upper surface drawing with diagonal lines) must be used as (Note 6) below while electrically insulated from outside.

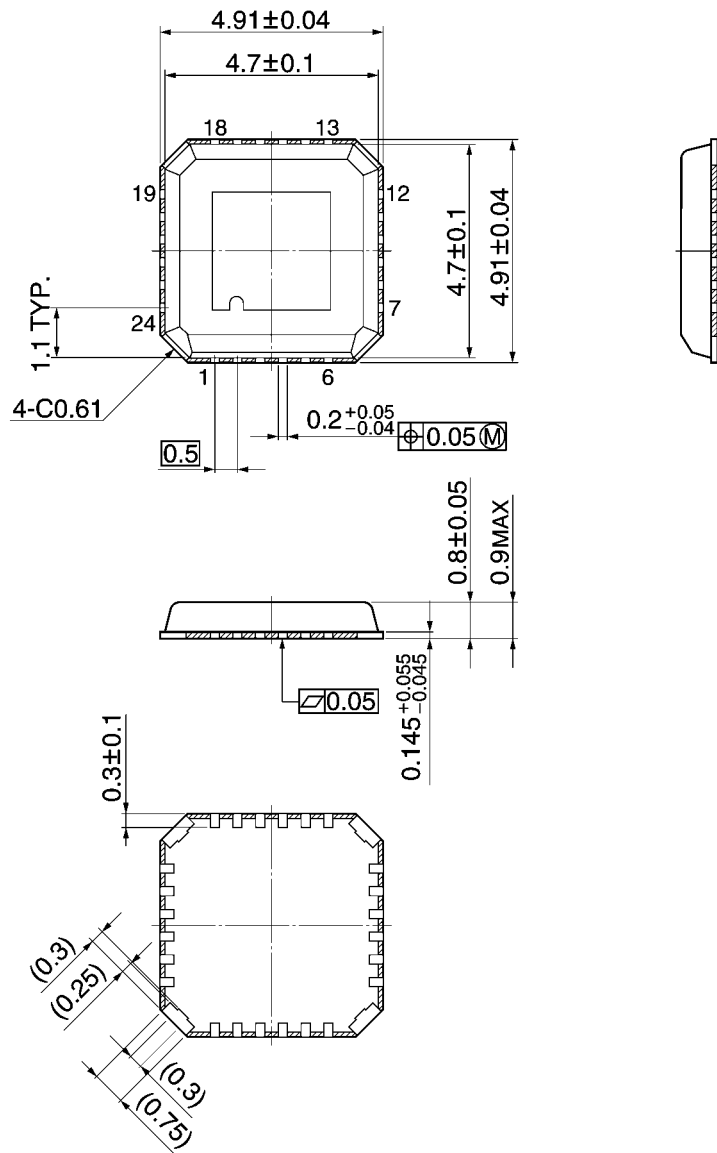
Note 6: Ensure that the island section (the section shown on the lower surface drawing with diagonal lines) does not come into contact with solder from through-holes on the board layout.

- When mounting or soldering, take care to ensure that neither static electricity nor electrical overstress is applied to the IC (measures to prevent anti-static, leaks, etc.).
- When incorporating into a set, adopt a set design that does not apply voltage directly to the island section.

Package Dimensions

QON24-P-0505-0.50

Unit: mm



Note 1) The solder plating portion in four corners of the package shall not be treated as an external terminal.

Note 2) Don't carry out soldering to four corners of the package.

Note 3)  area : Resin surface

Weight: 0.05 g (typ.)

RESTRICTIONS ON PRODUCT USE

030619EBA

- The information contained herein is subject to change without notice.
- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of TOSHIBA or others.
- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- The products described in this document are subject to the foreign exchange and foreign trade laws.
- TOSHIBA products should not be embedded to the downstream products which are prohibited to be produced and sold, under any law and regulations.